

# Global Wire Bonder Equipment Market Data Survey Report 2025

<https://marketpublishers.com/r/G0DC64783BCEN.html>

Date: October 2017

Pages: 85

Price: US\$ 1,500.00 (Single User License)

ID: G0DC64783BCEN

## Abstracts

### Summary

Wire bonder equipment is the machinery used for making interconnects between an IC or any other semiconductor device at the time of packaging. This interconnection ensures the flow of electricity in the semiconductor device. The thin-wire used to make these connections are usually made of copper, gold, aluminum, or silver. Wire bonder equipment is part of the semiconductor assembly and packaging process.

The global Wire Bonder Equipment market will reach xxx Million USD in 2017 with CAGR xx% 2018-2025. The main contents of the report including:

Global market size and forecast

Regional market size, production data and export & import

Key manufacturers (manufacturing sites, capacity and production, product specifications etc.)

Average market price by SUK

Major applications

Key manufacturers are included based on manufacturing sites, capacity and production, product specifications etc.:

ASM Pacific Technology

Kulicke& Soffa

Palomar Technologies

Besi

DIAS Automation

F&K Delvotec Bondtechnik

Hesse

Hybond

SHINKAWA Electric

Toray Engineering

West Bond

Major applications  
as follows:

Integrated Device Manufacturers (IDMs)

Outsourced Semiconductor Assembly and Test (OSAT)

Regional market size, production data and export & import:

Asia-Pacific

North America

Europe

South America

Middle East & Africa

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